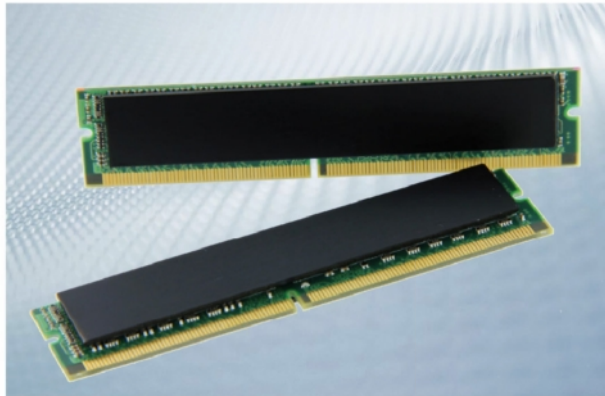




Virtium

... Because we know you needed it yesterday!

4GB DDR3 ECC UNBUFFERED ULP Mini-DIMM



DESCRIPTION:

Virtium Technology offers the industry's first 4GB DDR3 ECC UNBUFFERED Mini-DIMM available in its Ultra-Low Profile (ULP) 17.78mm (0.700-inch) form factor. Virtium's DDR3 memory module is an enhanced VLP MiniDIMM design that uses cost-effective mainstream 2Gbit DDR3 DRAM monolithic package components and features a minimal module thickness of 3.56mm (0.140-inch).

The Virtium 4GB DDR3 ULP is an optimal solution for wide range of space-constrained embedded systems that require reliable high-speed computing performance and low power.

Virtium delivers a comprehensive selection of module enhancements designed for rugged, mission-critical industrial applications. Additional services include extreme temperature testing, thermal management methodologies, conformal coating, underfill, and module anchor solutions for high-vibration environments.

FEATURES:

- DDR3 ECC UNBUFFERED Ultra-low profile (ULP) Mini-DIMM
- 2Gbit monolithic DRAM x8 non-stacked
- Module Speed Support: PC3-6400 @ CL6; PC3-8500 @ CL7; PC3-10600 @ CL9
- Single module per channel: 2.27W to 2.61W
- Dual module per channel: 3.62W to 4.10W
- Lead-free, RoHS compliant
- Available options: Thermal heat-spreader, thermal Sensor, conformal coating, underfill protection

BENEFITS:

- Cost-effective, single die monolithic package design
- High-speed computing performance
- Optimized for efficient thermal management max. airflow for dual side-by-side population of two 4GB modules in 22.5 degree angle socket
- Saves valuable board real estate with VLP form factor module
- Extended temp. screening: -40°C to +85°C

APPLICATIONS:

- AdvancedTCA Blades
- Double-Wide AdvancedMC Blades
- Ethernet Switches, Routers and Blades
- PCI Raid Cards

4GB DDR3 ULP ECC Unbuffered Mini-DIMM

DENSITY	HEIGHT	THICKNESS	MAX SPEED	COMP. DENSITY	COMP. PACKAGE	COMP. CONFIG.	MODULE RANKS	CL	PART NUMBER
4GB	17.78mm (0.700")	3.40mm (0.134")	PC3-12800	2Gbit	Monolithic	x8	2	11	VL51B5263F-K0S
4GB	17.78mm (0.700")	3.40mm (0.134")	PC3-10600	2Gbit	Monolithic	x8	2	9	VL51B5263F-K9S
4GB	17.78mm (0.700")	3.40mm (0.134")	PC3-8500	2Gbit	Monolithic	x8	2	7	VL51B5263F-F8S
4GB	17.78mm (0.700")	3.40mm (0.134")	PC3-6400	2Gbit	Monolithic	x8	2	6	VL51B5263F-E7S

Mechanical Outlines



Unit	Width	Height	Thickness
Inches	3.228	0.700	0.134
Millimeters	82.00	17.78	3.40

Additional Virtium Memory Products

4GB DDR3 VLP ECC Registered Mini-DIMM

DENSITY	HEIGHT	THICKNESS	MAX SPEED	COMP. DENSITY	COMP. PACKAGE	COMP. CONFIG.	MODULE RANKS	CL	PART NUMBER
4GB	18.3mm (0.72")	3.40mm (0.134")	PC3-12800	2Gbit	Monolithic	x8	2	11	VL53B5263E-K0S
4GB	18.3mm (0.72")	3.40mm (0.134")	PC3-10600	2Gbit	Monolithic	x8	2	9	VL53B5263E-K9S
4GB	18.3mm (0.72")	3.40mm (0.134")	PC3-8500	2Gbit	Monolithic	x8	2	7	VL53B5263E-F8S
4GB	18.3mm (0.72")	3.40mm (0.134")	PC3-6400	2Gbit	Monolithic	x8	2	6	VL53B5263E-E7S



Virtium Technology provides memory and solid state storage solutions for single board computers and high-reliability systems.

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